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BOX -- 10/785,046

Client/Matter: 081468-0308294

## IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A method of manufacturing a component that will, in use, experience a thermal load and will be operated at a mean operating temperature, the method comprising:

selecting a material having a coefficient of thermal expansion having a zero-crossing at a first temperature;

manufacturing the component using the selected material at a second temperature, wherein the first temperature is between the second temperature and the mean operating temperature, so as to minimize deformation of the component at the mean operating temperature.

- 2. (Original) A method according to claim 1, wherein the first temperature is equal to the average of the second temperature and the mean operating temperature.
- 3. (Original) A method according to claim 1, wherein the integral of the coefficient of thermal expansion of the selected material from the second temperature to the mean operating temperature is substantially zero.
- 4. (Original) A method according to claim 1, wherein the selected material is a material having a low coefficient of thermal expansion.
- 5. (Original) A method according to claim 1, wherein the selected material is a material having a substantially zero coefficient of thermal expansion.
- 6. (Original) A method according to claim 5, wherein the selected material is a glass or a glass-ceramic comprising additives to provide the coefficient of thermal expansion.
- 7. (Original) A method according to claim 1, wherein the second temperature is adjusted to enable use of a material having a coefficient of thermal expansion zero-crossing temperature that is fixed or of a limited variability.

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8. (Original) A component for use in a lithographic apparatus, the apparatus being configured to project a patterned beam of radiation onto a target portion of a substrate, wherein the component is made of a material having a coefficient of thermal expansion having a zero-crossing at a first temperature between a second temperature at which the component is manufactured and a mean operating temperature of the component.

- 9. (Original) A component according to claim 8, wherein the first temperature is equal to the average of the second temperature and the mean operating temperature.
- 10. (Original) A component according to claim 8, wherein the integral of the coefficient of thermal expansion of the material from the second temperature to the mean operating temperature is substantially zero.
- 11. (Original) A component according to claim 8, wherein the material is a material having a low coefficient of thermal expansion.
- 12. (Original) A component according to claim 8, wherein the material is a material having a substantially zero coefficient of thermal expansion.
- 13. (Original) A component according to claim 8, wherein the component is an optical component in at least one of a radiation system and a projection system of the lithographic apparatus.
- 14. (Original) A component according to claim 13, wherein the optical component is an optical element in the at least one of the radiation system and the projection system that experiences in use a highest thermal load.
- 15. (Original) A component according to claim 13, wherein the optical component is a

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- 16. (Original) A component according to claim 15, wherein the mirror comprises a substrate manufactured from a material having a low coefficient of thermal expansion and a multilayer stack.
- 17. (Original) A component according to claim 15, wherein the mirror comprises a substrate manufactured from a material having a substantially zero coefficient of thermal expansion and a multilayer stack.
- 18. (Original) A lithographic apparatus, comprising:
  - a radiation system configured to provide a beam of radiation;
- a support configured to support a patterning device, the patterning device configured to pattern the beam according to a desired pattern;
  - a substrate table configured to hold a substrate;
- a projection system configured to project the patterned beam of radiation onto a target portion of the substrate, wherein at least one component in the apparatus that in use experiences a thermal load is made of a low coefficient of thermal expansion material having a coefficient of thermal expansion having a zero-crossing at a temperature between a manufacturing temperature and a mean operating temperature of the at least one component.
- 19. (Previously presented) A device manufacturing method, comprising. providing a beam of radiation using a radiation system; using patterning means to endow the beam of radiation with a pattern in its cross-section;

projecting the patterned beam of radiation onto a target portion of a layer of radiationsensitive material at least partially covering a substrate using a projection system, wherein at
least one component in at least one of the radiation system and the projection system
experiencing a thermal load has a mean operating temperature and is made of a low
coefficient of thermal expansion material such that a coefficient of thermal expansion zerocrossing temperature of the material is between a manufacturing temperature of the at least
one component and the mean operating temperature.

20. (New) A component according to claim 8, wherein the material is a glass or a glass-ceramic comprising additives to provide the coefficient of thermal expansion.